



## D-band CMOS Vector Modulator-Based Phase Shifter for Millimeter-Wave Imaging System



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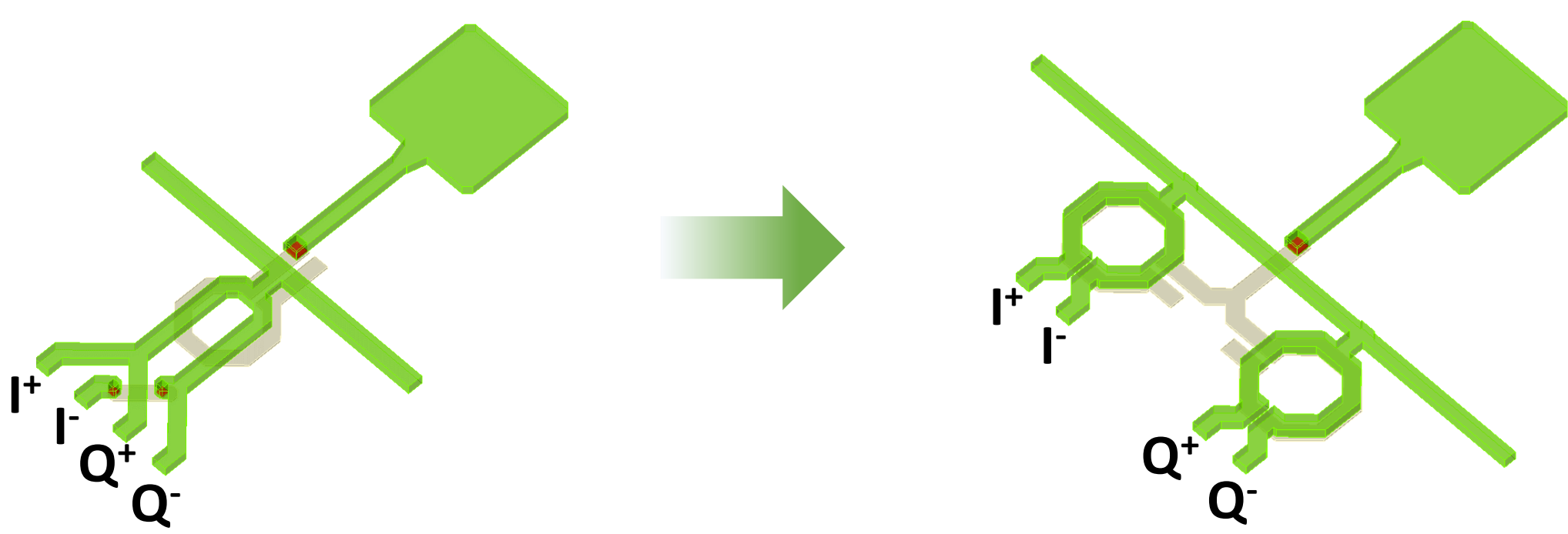
### Motivate

#### ● Millimeter-wave Imaging Systems using Polarization

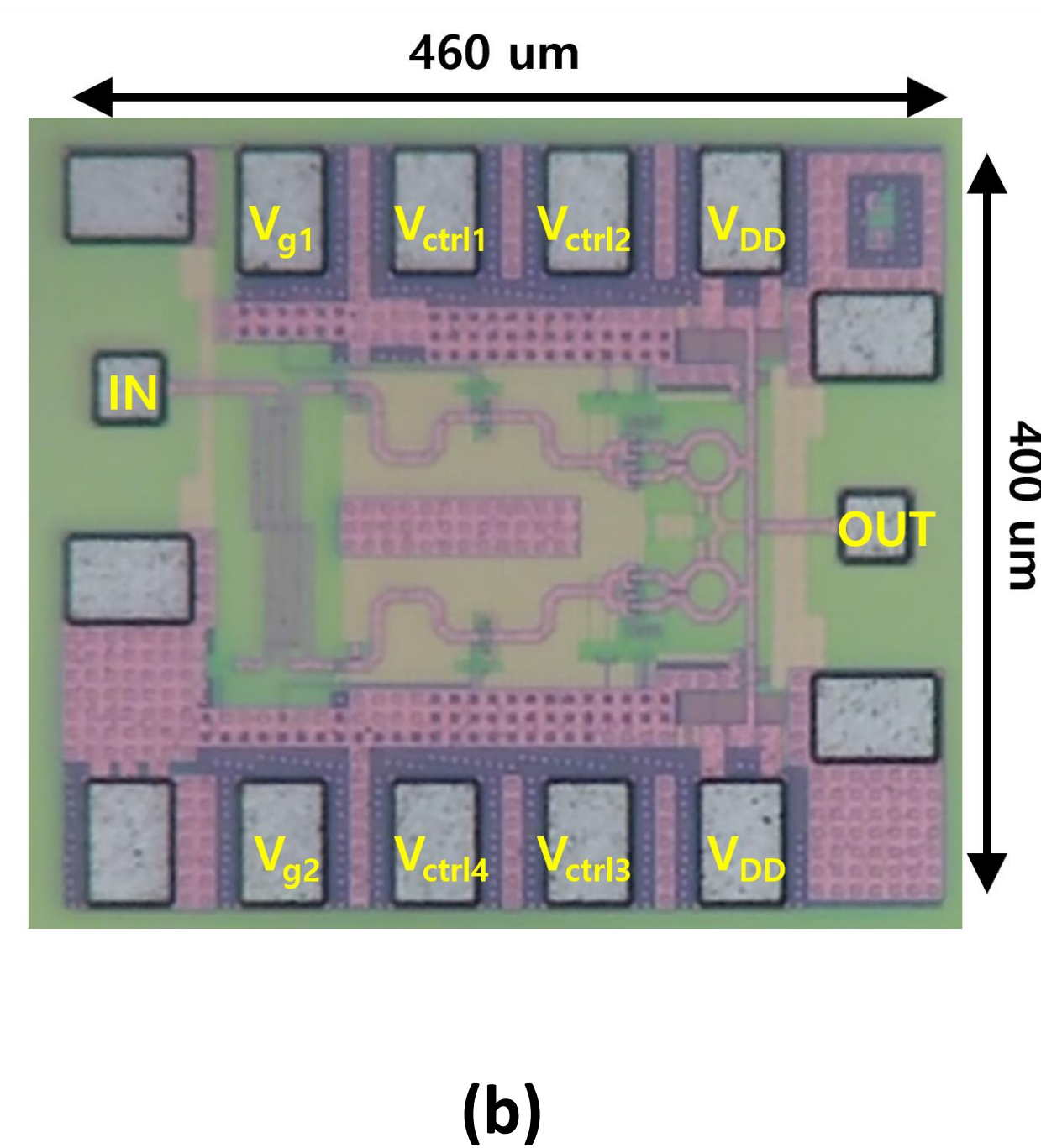
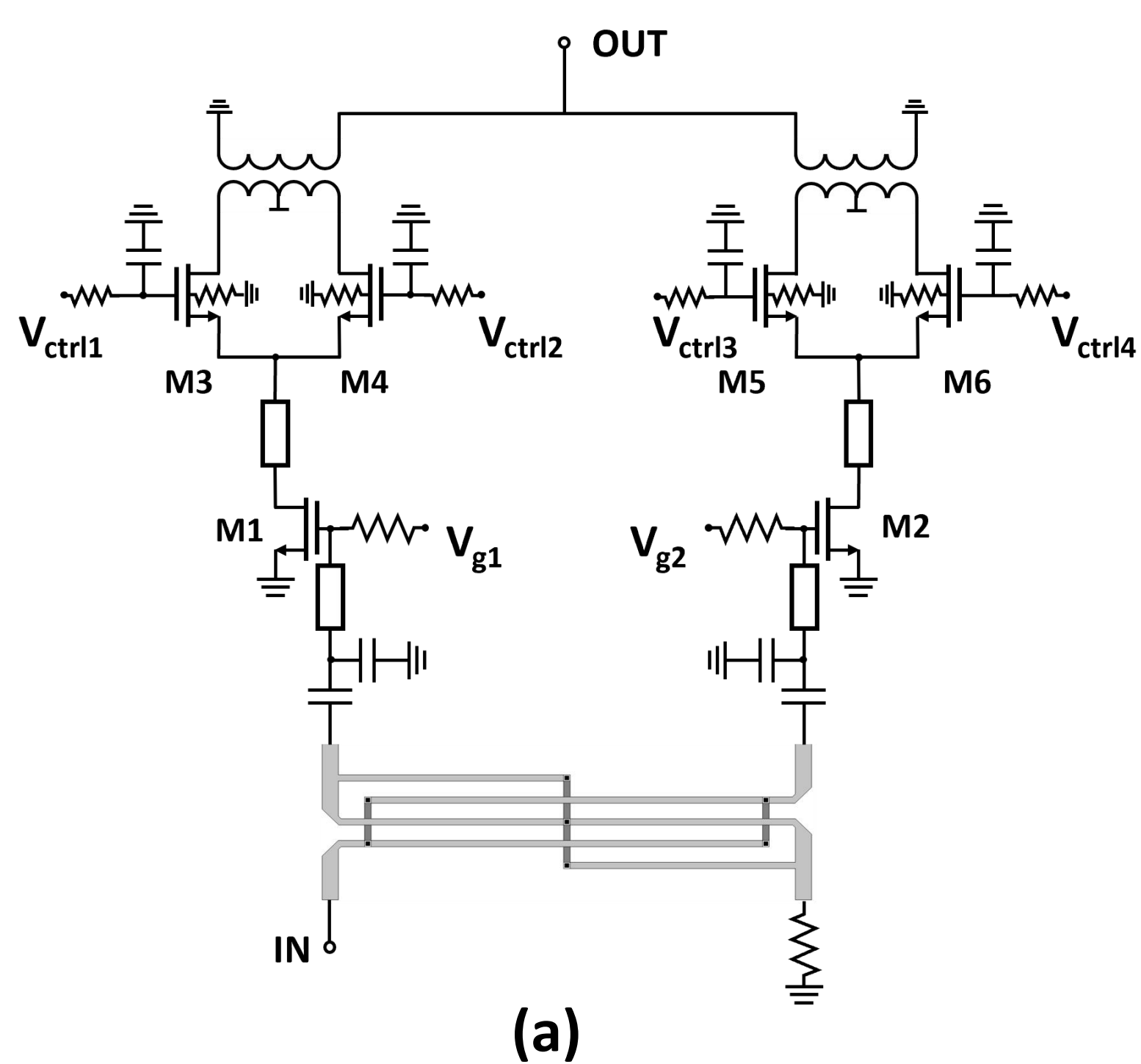
- **By controlling polarization of transmitted signal**, the detection of internal material properties **at specific frequencies improves image quality**.
- **Due to the high attenuation of millimeter-waves in the air and high-transmission power is advantages in imaging systems**, implementing a high-power transmitter is required.
- **A high-power phase shifter capable of controlling transmission signal polarization** is proposed for imaging systems.

### Methods

#### ● Design of Vector Modulated type Phase Shifter



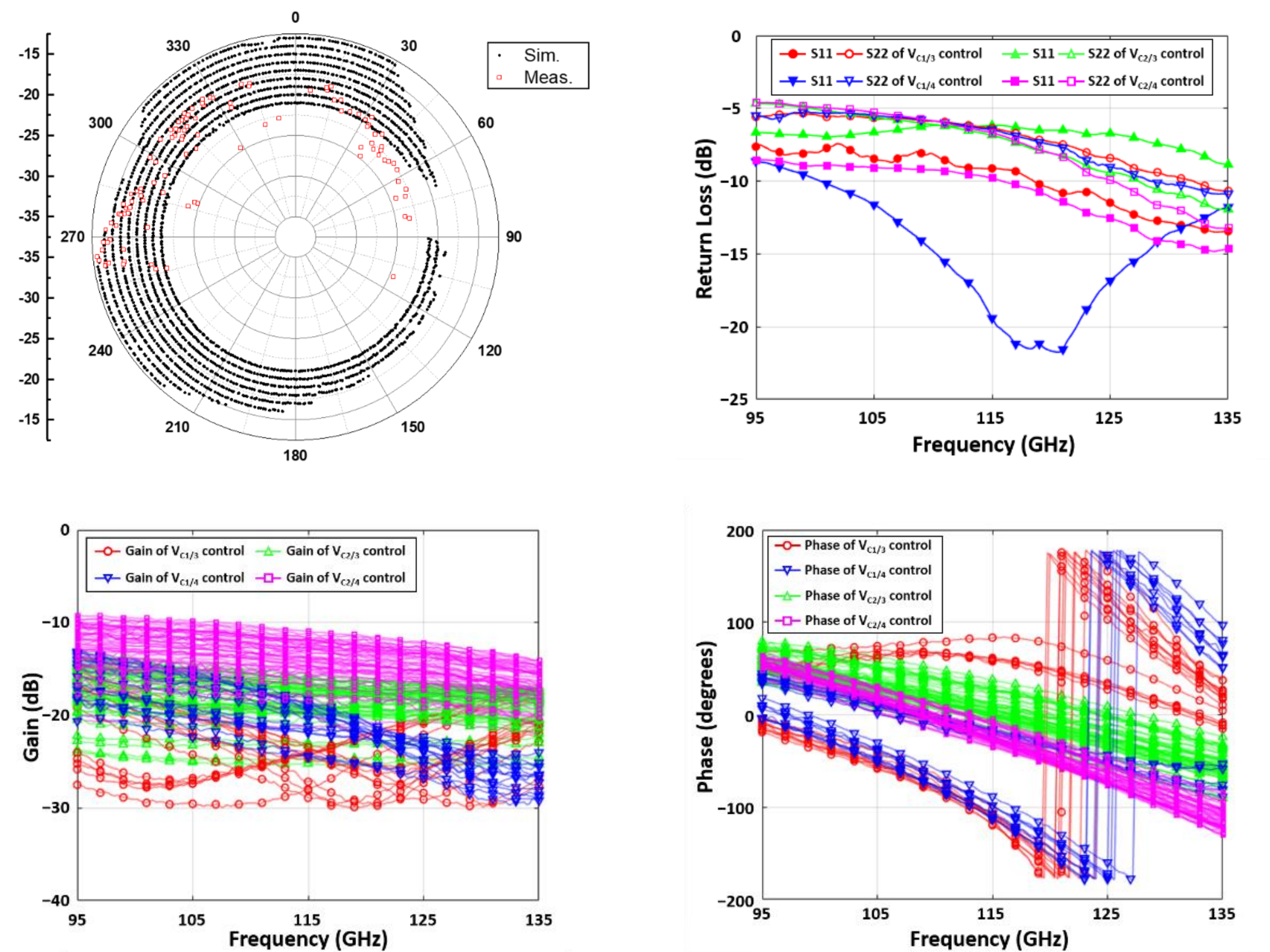
- By using Lange coupler, the low amplitude and phase imbalance **I/Q signal is implemented with small sizes (60μm×140μm)**.
- The single Gilbert-cell configuration VMPS being simpler than the double configuration leads to **low parasitic and improves gain**.
- Placing a transmission line between transconductance and switching-cells **enhances VGA gain and linearity by using resonance with parasitic capacitance [2]**.
- By modifying current direction, minimizing impedance variations caused by voltage control, and **optimizing output impedance matching**.



< (a) Schematic (b) Chip photograph of the proposed phase shifter >

### Results

#### ● Measurement Results of Proposed Phase Shifter



### Conclusion

- D-band CMOS VMPS is proposed effectively controls signal polarization in millimeter-wave imaging. The fabricated VMPS achieved a gain of -11 dB, an input  $P_{1dB}$  of 4 dBm, and consumed 22.8 mW.

| Ref.                         | TMTT 2015   | MWCL 2021    | MWCL 2020   | This work        |
|------------------------------|-------------|--------------|-------------|------------------|
| Tech.                        | 250 nm InP  | 55 nm BiCMOS | 130 nm SiGe | 65 nm CMOS       |
| Freq. (GHz)                  | 220–320     | 140–160      | 162–190     | 115–135          |
| $\Delta  S_{22} ^a$          | 4 dB        | 3.4 dB       | 4.9 dB      | 2 dB             |
| Gain (dB)                    | -13.7 ± 1.9 | -4.5         | -6.2        | -11 <sup>b</sup> |
| $IP_{1dB}$ (dBm)             | -0.7        | 2            | -13.5       | 7 <sup>c</sup>   |
| $P_{dc}$ (mW)                | 21.8–42     | 50           | 9.9–15.3    | 36               |
| Core Area (mm <sup>2</sup> ) | 0.23        | 0.05         | 0.07        | 0.053            |

<sup>a</sup> Maximum Variation <sup>b</sup> Maximum gain <sup>c</sup> at 125 GHz

### < Acknowledge >

- The chip fabrication and EDA tool usage were partly supported by the IC Design Education Center, Korea.